

Sample B.1
Sub
C1

24:60. The package of claim 57, wherein the second surface of the die pad is fully covered with the encapsulant material.

61. The package of claim 57, wherein the package body includes orthogonal exterior side surfaces adjacent to the first exterior surface of the package body, and a severed end of each contact is exposed in a common plane with one of the exterior side surfaces of the package body.

REMARKS

In the Office Action dated December 19, 2000, the Examiner required an election between package, leadframe, and method claims. In response thereto, Applicant has cancelled the pending claims, and added only package claims. Accordingly, the new claims are consistent with the restriction requirement.

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on 20 Feb, 2001.

James E. Parsons 20 Feb 01
Attorney for Applicant Date of Signature

Respectfully submitted,

James E. Parsons
James E. Parsons
Attorney for Applicant
Reg. No. 34,691

715897

LAW OFFICES OF
SKJERVEN MORRILL
MacPHERSON LLP

25 METRO DRIVE
SUITE 700
SAN JOSE, CA 95110
(408) 453-9200
FAX (408) 453-7979

B